Flash + Controller Part Numbering System
aka e-MMC and custom card part numbers

MT   FC   2G   A   A   M2 –   xx   ES

Micron Technology

FC = Flash + Controller
FP = Flash + Controller w/PCB

NAND Density

12M = 512MB	8G = 8GB	BA = BGA adapter
1G = 1GB	16G = 16GB	BG = BGA IC guide
2G = 2GB	32G = 32GB	
4G = 4GB	64G = 64GB	

NAND Component

Mark	Device
0	No silicon in package
A	2Gb, x8 1.8V
B	4Gb x8 3.3V
C	8Gb x8 3.3V
D	8Gb x8 3.3V
E	8Gb x8 3.3V
F	4Gb x8/x16
G	16Gb x8 3.3.V
H	32Gb x8 3.3V

Mark	Device
J	64Gb x8 3.3V
K	32Gb x8 3.3V
L	32Gb x8 3.3V
M	16Gb x8 3.3V
N	4Gb x8 3.3V
P	8Gb x8 3.3V
Q	32Gb x8 3.3V
R	64Gb x8 3.3V

Controller ID

Mark	Controller ID
0	No silicon in package
A	Rev 1
B	Rev 2
C	Rev 3
D	Rev 4
E	Rev 5
F	Rev 6
G	Rev 7
H	Rev 8
I	Rev 9
J	Rev 10
K	Rev 11
L	Rev 12
M	Rev 13
N	Rev 14
P	Rev 15
Q	Rev 16
R	Rev 17
S	Rev 18
T	Rev 19
W	Rev 20
X	Rev 21
Y	Rev 22
Z	Rev 23

Production Status
Blank = Production
ES = Engineering Sample
MS = Mechanical Sample

Operating Temperature Range
Blank = 0°C to +70°C
WT = Standard (–25°C to +85°C)
IT = Industrial (–40°C to +85°C)
AIT = Industrial (–40°C to +85°C + HR certified test flow)
AITI = Industrial (–40°C to +85°C + HR certified test flow)

Special Options
Blank = No special options
xx = Special options

Package Code (all packages are Pb-free)
AM = 153-ball VFBGA 11.5x13x1.0
DE = 153-ball LFBGA 11.5x13x1.4
DG = 169-ball LFBGA 12x16x1.5
DH = 169-ball LFBGA 12x18x1.4
DI =   169-ball TFBGA 12x16x1.2
DK = 169-ball LFBGA 12x16x1.4
DL = 169-ball TFBGA 12x18x1.2
DM = 153-ball TFBGA 11.5x13x1.2
DN = 169-ball LFBGA 14x18x1.4
DP = 169-ball LFBGA 14x18x1.7
DQ = 100-ball LBGA 14x18x1.4
DV = 169-ball VFBGA 12x16x1.0
EA = 153-ball WFBGA 11.5x13x0.8
EC = 169-ball WFBGA 14x18x0.8
ED = 169-ball VFBGA 14x18x1.0
EF = 169-ball TFBGA 14x18x1.2
EG = 169-ball WFBGA 12x16x0.8
EJ = 169-ball LFBGA 14x18x1.3

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